CMOS LSI

LC86P5032

8-Bit Single-Chip Microcontroller

Overview

The LC86P5032 microcontroller, a new addition to the LC865000 series, is a 8-bit single chip CMOS microcontroller with one-time PROM.

This microcontroller has the same function and pin assignment as for the LC865000 series mask ROM version, and a 32K-byte PROM.

The same DIP/QFP packages as for the LC865000 series are available for shipment. It is suitable for setting up the first release, for prototyping and developing and testing applications.

Features

(1) Option switching using PROM data
    The optional functions of the LC865000 series can be specified using PROM data.
    The functions of the trial products can be evaluated using a mass production board.
(2) Internal one-time PROM capacity   : 32768 bytes
(3) Internal RAM capacity   :   512 bytes

Mask ROM version	PROM capacity	RAM capacity
LC865032	32512 bytes	512 bytes
LC865028	28672 bytes	512 bytes
LC865024	24576 bytes	512 bytes
LC865020	20480 bytes	384 bytes
LC865016	16384 bytes	384 bytes
LC865012	12288 bytes	384 bytes
LC865008	8192 bytes	384 bytes

(4) Operating supply voltage   : 4.5 to 6.0 V
(5) Instruction cycle time   : 0.98 to 400 µs
(6) Operating temperature range   : –30°C to +70°C
(7) Pins and package compatible with the mask ROM version
(8) Applicable mask version   : LC865032/LC865028/LC865024/LC865020/LC865016/LC865012, LC865008
(9) Factory shipment   : DIP-64S
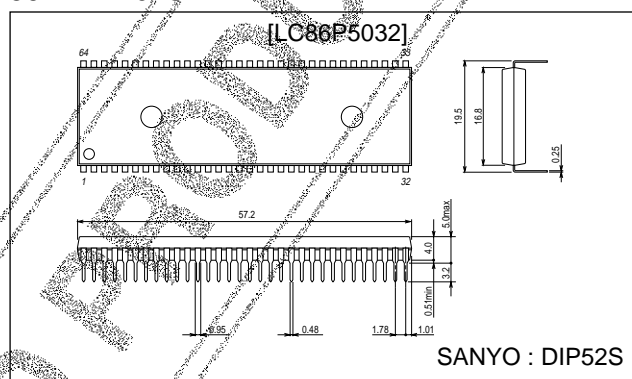   QFP-64E

Programming service

We offer various services at nominal charges. These include ROM writing, ROM reading, and package stamping and screening. Contact our local representatives for further information.
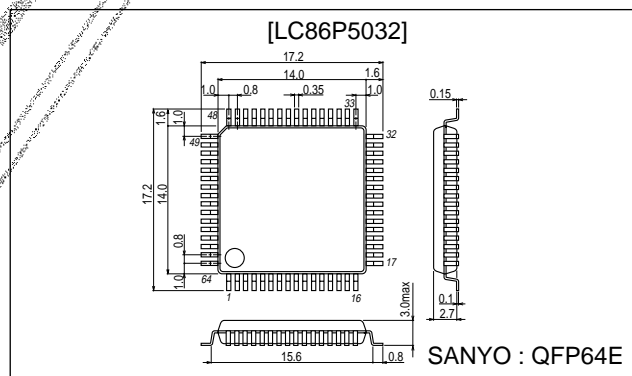
Package Dimensions

unit : mm

3071-DIP64S

[LC86P5032]

SANYO : DIP52S

unit : mm

3159-QFP64E

[LC86P5032]

SANYO : QFP64E

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Usage Notes

When using, please take note of the following.

(1) Differences between the LC86P5032 and the LC865000 series

Item	LC86P5032	LC865032/28/24/20/16/12/08
Port status at reset	Please refer to "Port status at reset" on the next page.	
Operation after releasing reset	The option is specified by degrees within 3 ms after applying a 'H' level to the reset pin. The program located at 00H is executed.	The program located at 00H is executed immediately after applying a 'H' level to the reset pin.
Operating voltage range (V_{DD})	4.5 to 6.0 V	2.7 to 6.0 V
Total output current [$\Sigma I_{OAH}(1)$] [$\Sigma I_{OAH}(1)$]		
Current drain [$I_{DDOP}(1)$] [$I_{DDOP}(2)$] [$I_{DDOP}(3)$] [$I_{DDOP}(4)$]	Refer to 'Electrical Characteristics' on the semiconductor news.	

• LC86P5032 Options

Option	Pins, Circuits	Option Settings
Configuration of input/output ports	Port 0 (Can be specified for each bit.)	1. Input : No pull-up MOS transistor Output : N-channel open drain 2. Input : Pull-up MOS transistor Output : CMOS
	Ports 1, 2 (Can be specified for each bit.)	1. Input : No programmable pull-up MOS transistor Output : N-channel open drain 2. Input : Programmable pull-up MOS transistor Output : CMOS
	Ports 3, 4, 5 (Can be specified for each bit.)	1. Input : No programmable pull-up MOS transistor Output : N-channel open drain 2. Input : Programmable pull-up MOS transistor Output : CMOS
Port 7 pull-up MOS transistor	Port 7 (Can be specified for each bit.)	1. Pull-up MOS transistor not provided 2. Pull-up MOS transistor provided *$\overline{P74}$ has no pull-up resistor option.

The port operation related to the option is different at reset. Please refer to the next table.

• Port configuration at reset

| Pin	Option settings	LC86P5032	LC865032/28/24/20/16/12/08
P0	Input : No pull-up MOS transistor Output : N-channel open drain	(Same as for the mask version)	Input mode without pull-up MOS transistor (Output is OFF)
	Input : Pull-up MOS transistor Output : CMOS	Input mode • The Pull-up MOS transistor is not present during reset or several hundred microseconds after releasing reset. After that, the pull-up MOS transistor is present. (Output is OFF)	Input mode with pull-up MOS transistor (Output is OFF)
P1, P2	Input : Programmable pull-up MOS transistor Output : N-channel open drain	(Same as for the mask version)	Input mode without pull-up MOS transistor (Output is OFF)
	Input : Programmable pull-up MOS transistor Output : CMOS	(Same as for the mask version)	Input mode without pull-up MOS transistor (Output is OFF)
P3, P4, P5	Input : Non-Programmable pull-up MOS transistor Output : N-channel open drain	(Same as for the mask version)	Input mode without pull-up MOS transistor (Output is OFF)
	Input : Programmable pull-up MOS transistor Output : CMOS	(Same as for the mask version)	Input mode without pull-up MOS transistor (Output is OFF)
P7	Pull-up MOS transistor not provided	(Same as for the mask version)	Input mode without pull-up MOS transistor
	Pull-up MOS transistor provided	Input mode • The pull-up MOS transistor is not present during reset or several hundred microseconds after releasing reset. After that, the pull-up MOS transistor is present.	Input mode with pull-up MOS transistor

(2) Option

The LC86P5032 uses 256 bytes addressed 7F00H to 7FFFH in program memory as option data area. This area does not affect the execution of the program but means that the LC865032 program memory is 32512 bytes addressed 0000H to 7EFFH.
The option data is written using the option specifying program "SU865000. EXE". The option data is linked to the program area by linkage loader "L865000. EXE".

(3) ROM space
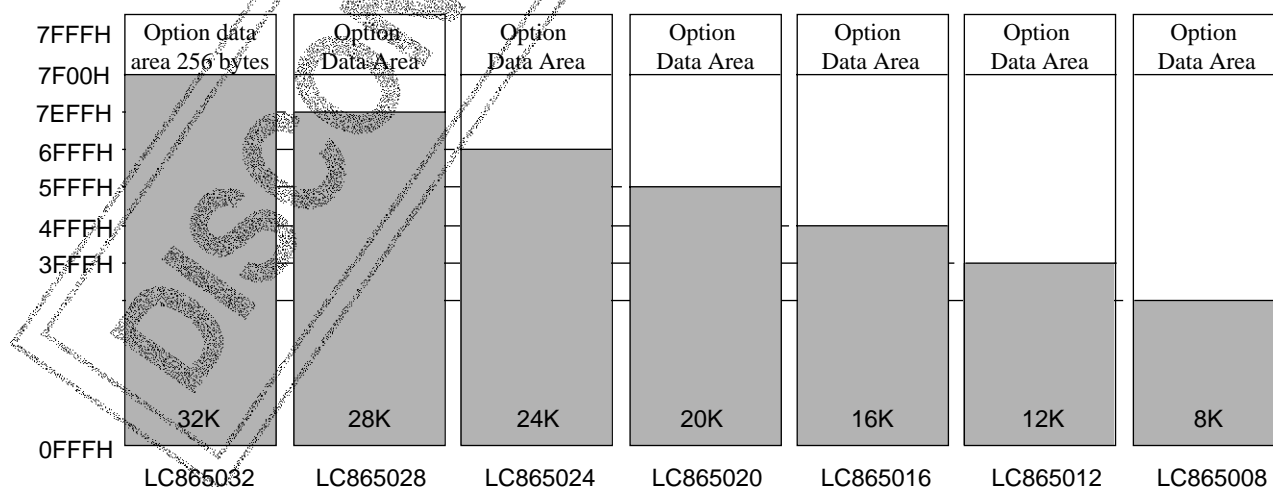
(4) Ordering information

　　　1. When ordering identical mask ROM and PROM devices simultaneously.

　　　　Provide an EPROM containing the target memory contents together with separate order forms for each of the mask ROM and PROM versions.

　　　2. When ordering a PROM device.

　　　　Provide an EPROM containing the target memory contents together with an order form.

How to Use

(1) Specification of options

　　　Programming data for the LC86P5032's EPROM is required.

　　　The debugged evaluation file (EVA file) must be converted to an INTEL-HEX formatted file (HEX file) with file converter program EVA2HEX.EXE. The HEX file is used as the programming data for the LC86P5032.

(2) How to program the EPROM

　　　The LC86P5032 can be programmed by an EPROM programmer with attachments W86EP5032D and W86EP5032Q.

　　　• Recommended EPROM programmer

Supplier	EPROM programmer
Advantest	R4945, R4944, R4943
Andou	AF-9704
AVAL	PKW-1100, PKW-3000
Minato Electronics	MODEL 1890A

　　　• "27512 (Vp-p = 12.5 V) Intel high-speed programming" mode available. The address must be set to "0000H to 7FFFH" and the jumper (DASEC) must be set 'OFF' at programming.

(3) How to use the data security function

　　　"Data security" is a function to prevent EPROM data from being read.

　　　Instructions on using the data security function:

　　　　1. Set the jumper of attachment 'ON'.

　　　　2. Attempt to program the EPROM. The EPROM programmer will display an error. The error indication is a result of normal activity of the data security feature. This is not a problem with the EPROM programmer chip.

Notes

• The data security function is not carried out when the data of all addresses contain 'FF' at step 2 above.
• Data security cannot be executed when the sequential operation "BLANK=>PROGRAM=>VERIFY" is used at step 2 above.
• Set the jumper 'OFF' after execution of data security.

Pin 1　　　Data security OFF

W86EP5032D

Pin 1 mark

Pin 1　　　Data security OFF
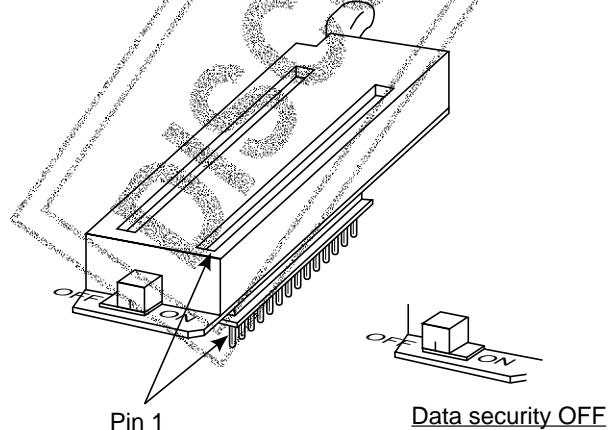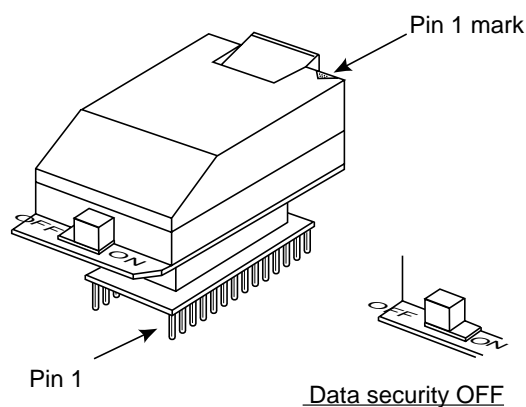
W86EP5032Q

Pin Assignment

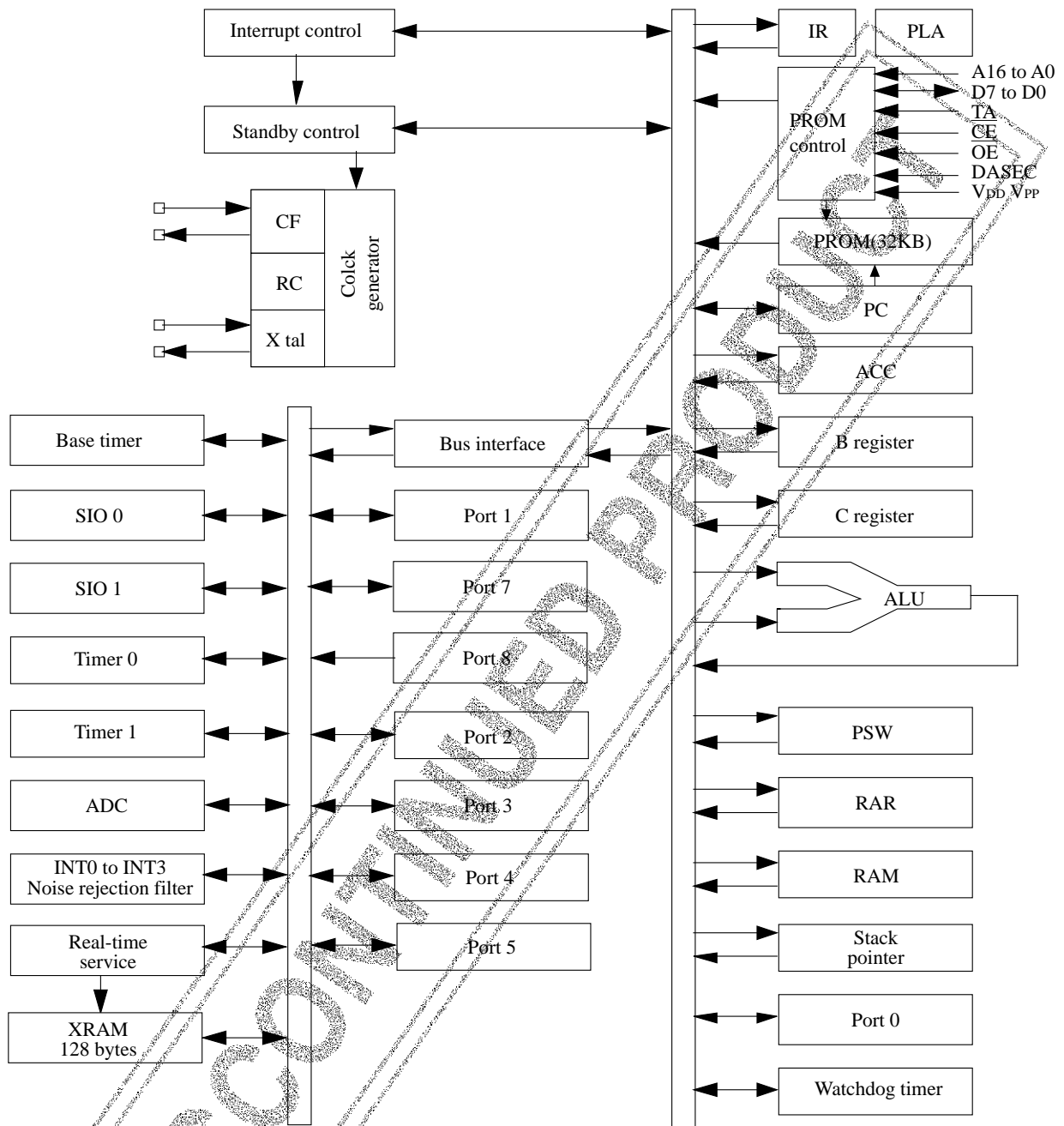| Pin	No.		No.	Pin
P10/SO0	1		64	P07
P11/SI0/SB0	2		63	P06
P12/SCK0	3		62	P05
P13/SO1	4		61	P04
P14/SI1/SB1	5		60	P03
P15/SCK1	6		59	P02
P16/BUZ	7		58	P01
P17/PWM	8		57	P00
TEST1	9		56	P27
$\overline{\text{RES}}$	10		55	P26
XT1/$\overline{\text{P74}}$	11		54	P25
XT2	12		53	P24
V$_{SS}$	13		52	P23
CF1	14		51	P22
CF2	15		50	P21
V$_{DD}$	16		49	P20
P80/AN0	17		48	V$_{DD}$V$_{PP}$
P81/AN1	18		47	V$_{SS}$
P82/AN2	19		46	P51
P83/AN3	20		45	P50
P84/AN4	21		44	P47
P85/AN5	22		43	P46
P86/AN6	23		42	P45
P87/AN7	24		41	P44
P70/INT0	25		40	P43
P71/INT1	26		39	P42
P72/INT2/T0IN	27		38	P41
P73/INT3/T0IN	28		37	P40
P30	29		36	P37
P31	30		35	P36
P32	31		34	P35
P33	32		33	P34

Top view

SANYO : DIP64S

Pin Assignment
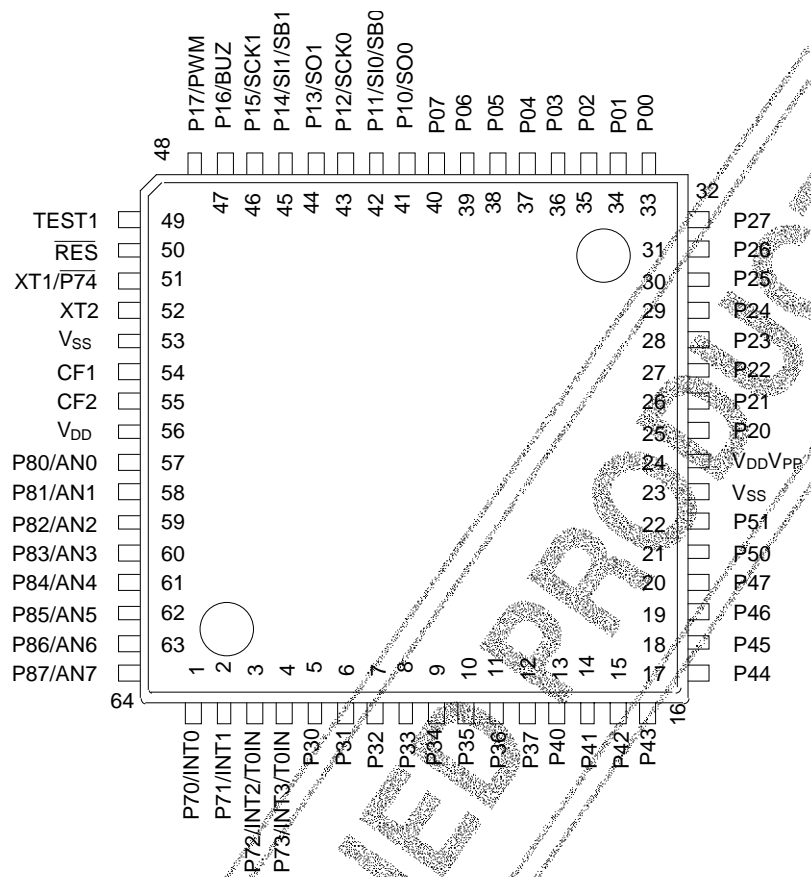
Top view

SANYO : QFP64E

System Block Diagram

LC86P5032 Pin Description

Pin name	I/O	Function description	Option	Function in PROM mode
V$_{SS}$		Power supply pin($-$)		
V$_{DD}$		Power supply pin($+$)		
V$_{DD}$V$_{PP}$		Power supply pin($+$)		Power for programming

PORT0
P00 to P07
	I/O	• 8-bit input/output port
		• Input for port 0 interrupt
		• Input/output in nibble units
		• Input for HOLD release
			• Pull-up resistor :
			  Present/Not present
			
			• Output form : CMOS/
			  N-channel open drain.	

PORT1
P10 to P17
	I/O	• 8-bit input/output port
		• Data direction can be specified for each bit.
		• Other pin functions
		  P10 : SIO0 data output
		  P11 : SIO0 data input/bus input/output
		  P12 : SIO0 clock input/output
		  P13 : SIO1 data output
		  P14 : SIO1 data input/ bus input/output
		  P15 : SIO1 clock input/output
		  P16 : Buzzer output
		  P17 : Timer 1 output (PWM output)
			Output form : CMOS/
			N-channel open drain
				Data input/output
				• D0 to D7

PORT2 P20 to P27	I/O	• 8-bit input/output port • Data direction can be specified for each bit.	Output form : CMOS/ N-channel open drain	
PORT3 P30 to P37	I/O	• 8-bit input/output port • Data direction can be specified for each bit. • 15 V withstand at N-ch open-drain output	Output form : CMOS/ N-channel open drain	Address input • A7 to A0
PORT4 P40 to P47	I/O	• 8-bit input/output port • Data direction can be specified for each bit. • 15 V withstand at N-ch open-drain output	Output form : CMOS/ N-channel open drain	Address input • A14 to A8 (∗5) • P47 : TA (∗4)
PORT5 P50 to P51	I/O	• 2-bit input/output port. • Data direction can be specified for each bit. • 15 V withstand at N-ch open-drain output	Output form : CMOS/ N-channel open drain	

PORT7
 	
P70
 	
P71 to P74
	I/O
	
	I
		• 5-bit input port
		• Other pin functions
		P70 : INT0 input/HOLD release/N-channel
		  Tr. output for watchdog timer.
		P71 : INT 1 input/HOLD release.
		P72 : INT 2 input/timer 0 event input.
		P73 : INT 3 input with noise filter/timer 0
		  event input.
		P74 : Input pin XT1 for 32.768 kHz crystal
		  oscillation
		• Interrupt received format, vector address.
			Pullup resistor :
			Present/Not present
			(P70, 71, 72, 73)
			∗ P74 has no pull-up
			  resistor.
				Input of PROM control signal
				• DASEC (∗1)
				• OE (∗2)
				• CE (∗3)

	Rising	Falling	Rising & falling	High level	Low level	Vector
INT0	Enable	Enable	Disable	Enable	Enable	03H
INT1	Enable	Enable	Disable	Enable	Enable	0BH
INT2	Enable	Enable	Enable	Disable	Disable	13H
INT3	Enable	Enable	Enable	Disable	Disable	1BH

| Pin name	I/O	Function description	Option	Function in PROM mode
PORT8 P80 to P87	I	• 8-bit input port • Other functions AD input port (8 port pins)		
$\overline{\text{RES}}$	I	Reset pin		
TEST1	O	Test pin Should be left open.		
XT1/P74	I	• Input pin for 32.768 kHz crystal oscillation • Other function : Input port $\overline{\text{P74}}$ When not used, connect to V_{DD}.		
XT2	O	Output pin for 32.768 kHz crystal oscillation When not used, should be left open.		
CF1	I	Input pin for ceramic resonator oscillation		
CF2	O	Output pin for ceramic resonator oscillation		

• All port options can be specified in bit units.

*1 Memory select input for data security
*2 Output enable input
*3 Chip enable input
*4 TA → PROM control signal input
*5 A14 → Address input

• Connect as shown in the following figure to reduce noise into V_{DD} pin.
  Short-circuit the V_{DD} pin to the $V_{DD}V_{PP}$ pin.
  Short-circuit the V_{SS} pin to the V_{SS} pin.
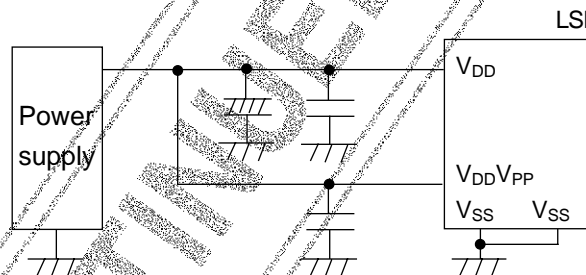
1. Absolute Maximum Ratings at $Ta = 25°C$, $V_{SS} = 0\ V$

Parameter		Symbol	Pins	Conditions	Ratings				Unit
					V_{DD}[V]	min	typ	max	
Supply voltage		V_{DD} max	V_{DD}, $V_{DD}V_{PP}$	$V_{DD} = V_{DD}V_{PP}$		−0.3		+7.0	V
Input voltage		V_I(1)	• Ports 71, 72, 73, $\overline{74}$ • Port 8 • $\overline{RES}$			−0.3		V_{DD}+0.3	
Input/output voltage		V_{IO}(1)	• Ports 0, 1, 2 • Ports 3, 4, 5 of CMOS output			−0.3		V_{DD}+0.3	
		V_{IO}(2)	• Ports 3, 4, 5 of open-drain output			−0.3		15	
High-level output current	Peak output current	I_{OPH}(1)	Ports 0, 1, 2, 3, 4, 5	• CMOS output • At each pin		−4			mA
	Total output current	ΣI_{OAH}(1)	Ports 0, 1, 2	Total of all pins		−25			
		ΣI_{OAH}(2)	Ports 3, 4, 5	Total of all pins		−20			
Low-level output current	Peak output current	I_{OPL}(1)	Ports 0, 1, 2, 3, 4, 5	At each pin				20	
		I_{OPL}(2)	Port 70	At each pin				15	
	Total output current	ΣI_{OAL}(1)	Ports 0, 1, 70	Total of all pins				40	
		ΣI_{OAL}(2)	Port 2	Total of all pins				40	
		ΣI_{OAL}(3)	Ports 3, 4, 5	Total of all pins				80	
Power dissipation (max.)		Pd max(1)	DIP64S	Ta = −30°C+70°C				720	mW
		Pd max(2)	QFP64E	Ta = −30°C+70°C				420	
Operating temperature range		Topr				−30		70	°C
Storage temperature range		Tstg				−65		150	

2.   Recommended Operating Range at Ta $= -30°C$ to $+70°C$, $V_{SS} = 0$ V

Parameter	Symbol	Pins	Conditions	V_{DD}[V]	min	typ	max	Unit
						Ratings		
Operating voltage range	$V_{DD}(1)$	V_{DD}	$0.98\ \mu s \leq tCYC$ $tCYC \leq 400\ \mu s$		4.5		6.0	V
HOLD voltage	V_{HD}	V_{DD}	RAM and registers retain their pre-HOLD mode values.		2.0		6.0	
Input high voltage	$V_{IH}(1)$	Port 0 (Schmitt)	Output disabled	4.5 to 6.0	$0.4V_{DD}$ $+0.9$		V_{DD}	
	$V_{IH}(2)$	• Ports 1, 2 • Ports 72, 73 (Schmitt)	Output disabled	4.5 to 6.0	$0.75V_{DD}$		V_{DD}	
	$V_{IH}(3)$	• Port 70 Port input/interrupt. • Port 71 • $\overline{RES}$ (Schmitt)	Output N-channel transistor OFF	4.5 to 6.0	$0.75V_{DD}$		V_{DD}	
	$V_{IH}(4)$	Port 70 Watchdog timer	Output N-channel transistor OFF	4.5 to 6.0	$0.9V_{DD}$		V_{DD}	
	$V_{IH}(5)$	• Port $\overline{74}$ • Port 8	Output N-channel transistor OFF	4.5 to 6.0	$0.75V_{DD}$		V_{DD}	
	$V_{IH}(6)$	Ports 3, 4, 5 of CMOS output (Schmitt)	Output disabled	4.5 to 6.0	$0.75V_{DD}$		V_{DD}	
	$V_{IH}(7)$	Ports 3, 4, 5 of open drain output (Schmitt)	Output disabled	4.5 to 6.0	$0.75V_{DD}$		13.5	
Input low voltage	$V_{IL}(1)$	Port 0 (Schmitt)	Output disabled	4.5 to 6.0	V_{SS}		$0.2V_{DD}$	
	$V_{IL}(2)$	• Ports 1, 2, 3, 4, 5 • Ports 72,73 (Schmitt)	Output disabled	4.5 to 6.0	V_{SS}		$0.25V_{DD}$	
	$V_{IL}(3)$	• Port 70 Port input/interrupt. • Port 71 • $\overline{RES}$ (Schmitt)	N-channel transistor OFF	4.5 to 6.0	V_{SS}		$0.25V_{DD}$	
	$V_{IL}(4)$	Port 70 Watchdog timer	N-channel transistor OFF	4.5 to 6.0	V_{SS}		$0.8V_{DD}$ -1.0	
	$V_{IL}(5)$	• Port $\overline{74}$ • Port 8	N-channel transistor OFF	4.5 to 6.0	V_{SS}		$0.25V_{DD}$	
Operation cycle time	tCYC			4.5 to 6.0	0.98		400	μs

Parameter	Symbol	Pins	Conditions	V$_{DD}$[V]	Ratings min	Ratings typ	Ratings max	Unit
Oscillation frequency range (Note 1)	FmCF(1)	CF1, CF2	• 12 MHz (ceramic resonator oscillation). • Refer to Figure 1.	4.5 to 6.0	11.76	12	12.24	MHz
	FmCF(2)	CF1, CF2	• 3 MHz (ceramic resonator oscillation). • Refer to Figure 1.	4.5 to 6.0	2.94	3	3.06	
	FmRC		RC oscillation	4.5 to 6.0	0.4	0.8	2.0	
	FsXtal	XT1, XT2	• 32.768 kHz (crystal oscillation). • Refer to Figure 2.	4.5 to 6.0		32.768		kHz
Oscillation stable time period (Note 1)	tmsCF(1)	CF1, CF2	• 12 MHz (ceramic resonator oscillation). • Refer to Figure 3.	4.5 to 6.0		0.03	0.5	ms
	tmsCF(2)	CF1, CF2	• 3 MHz (ceramic resonator oscillation). • Refer to Figure 3.	4.5 to 6.0		0.2	2	
	tssXtal	XT1, XT2	• 32.768 kHz (crystal oscillation). • Refer to Figure 3.	4.5 to 6.0		1	1.5	s

(Note 1) The oscillation constants are shown on Table 1 and Table 2.

3. Electrical Characteristics at Ta= –30°C to +70°C , V_{SS} = 0 V

Parameter	Symbol	Pins	Conditions	Ratings				Unit
				V_{DD} [V]	min	typ	max	
Input high current	$I_{IH}(1)$	• Ports 3, 4, 5 at open-drain output	• Output disabled • V_{IN} = 13.5 V (including off-state leak current of output transistor)	4.5 to 6.0			5	μA
	$I_{IH}(2)$	• Port 0 without pull-up MOS transistor • Ports 1, 2, 3, 4, 5	• Output disabled • Pull-up MOS transistor OFF. V_{IN} = V_{DD} (including off-state leak current of output transistor)	4.5 to 6.0			1	
	$I_{IH}(3)$	• Ports 70, 71, 72, 73 without pull-up MOS transistor • Port 8	V_{IN} = V_{DD}	4.5 to 6.0			1	
	$I_{IH}(4)$	• $\overline{RES}$	V_{IN} = V_{DD}	4.5 to 6.0			1	
Input low current	$I_{IL}(1)$	• Ports 1, 2, 3, 4, 5 • Port 0 without pull-up MOS transistor	• Output disabled • Pull-up MOS transistor OFF. V_{IN} = V_{SS} (including off-state leak current of output transistor)	4.5 to 6.0	–1			
	$I_{IL}(2)$	• Ports 70, 71, 72, 73 without pull-up MOS transistor • Port 8	V_{IN} = V_{SS}	4.5 to 6.0	–1			
	$I_{IL}(3)$	• $\overline{RES}$	V_{IN} = V_{SS}	4.5 to 6.0	–1			
Output high voltage	$V_{OH}(1)$	• Ports 0, 1, 2, 3, 4, 5 at CMOS output	I_{OH} = –1.0 mA	4.5 to 6.0	V_{DD}–1			V
	$V_{OH}(2)$		I_{OH} = –0.1 mA	4.5 to 6.0	V_{DD}–0.5			
Output low voltage	$V_{OL}(1)$	Ports 0, 1, 2, 3, 4, 5	I_{OL} = 10 mA	4.5 to 6.0			1.5	V
	$V_{OL}(2)$		I_{OL} = 1.6 mA	4.5 to 6.0			0.4	
	$V_{OL}(3)$	Port 70	I_{OL} = 1 mA	4.5 to 6.0			0.4	
	$V_{OL}(4)$		I_{OL} = 0.5 mA	4.5 to 6.0			0.4	
Pull-up MOS transistor resistance	Rpu	• Ports 0, 1, 2, 3, 4, 5 • Ports 70, 71, 72, 73	V_{OH} = 0.9 V_{DD}	4.5 to 6.0	15	40	70	kΩ
Hysteresis voltage	V_{HIS}	• Ports 0, 1, 2, 3, 4, 5 • Ports 70, 71, 72, 73 • $\overline{RES}$	Output disable	4.5 to 6.0		0.1V_{DD}		V
Pin capacitance	CP	All pins	• f = 1 MHz • Unmeasured input pins are set to V_{SS} level. • Ta = 25°C	4.5 to 6.0		10		pF

4. Serial Input/Output Characteristics at Ta = –30°C to +70°C , V_{SS} = 0 V

Parameter			Symbol	Pins	Conditions	Ratings				Unit
						V_{DD} [V]	min	typ	max	
Serial clock	Input clock	Cycle	tCKCY(1)	SCK0, SCK1	Refer to Figure 5.	4.5 to 6.0	2			tCYC
		Low-level pulse width	tCKL(1)			4.5 to 6.0	1			
		High-level pulse width	tCKH(1)			4.5 to 6.0	1			
	Output clock	Cycle	tCKCY(2)	SCK0, SCK1	• Use pullup resistor (1 kΩ) when set to open-drain output. • Refer to Figure 5.	4.5 to 6.0	2			
		Low-level pulse width	tCKL(2)			4.5 to 6.0		1/2tCKYC		
		High-level pulse width	tCKH(2)			4.5 to 6.0		1/2tCKYC		
Serial input	Data setup time		tICK	• SI0, SI1 • SB0, SB1	• Data set-up to SCK0, 1	4.5 to 6.0	0.1			µs
	Data hold time		tCKI		• Data hold from SCK0, 1 • Refer to Figure 5.	4.5 to 6.0	0.1			
Serial output	Output delay time (Serial clock is extrnal clock.)		tCKO(1)	• SO0, SO1 • SB0, SB1	• Use a pullup resistor (1 kΩ) when set to open-drain output.	4.5 to 6.0			7/12tCYC +0.2	
	Output delay time (Serial clock is internal clock.)		tCKO(2)		• Data hold from SCK0, 1 • Refer to Figure 5.	4.5 to 6.0			1/3tCYC +0.2	

5. Pulse Input Conditions at Ta = –30°C to +70°C, V$_{SS}$ = 0 V

Parameter	Symbol	Pins	Conditions		Ratings			Unit
				V$_{DD}$ [V]	min	typ	max	
High/low-level pulse width	tPIH(1) tPIL(1)	• INT0, INT1 • INT2/T0IN • INT3	• Interrupt acceptable • Timer 0 pulse countable	4.5 to 6.0	1			tCYC
	tPIH(2) tPIL(2)	INT3 (The noise rejection clock selected to 1/1.)	• Interrupt acceptable • Timer 0 pulse countable	4.5 to 6.0	2			
	tPIH(3) tPIL(3)	INT3 (The noise rejection clock selected to 1/16.)	• Interrupt acceptable • Timer 0 pulse countable	4.5 to 6.0	32			
	tPIL(4)	$\overline{\text{RES}}$	Reset acceptable	4.5 to 6.0	200			μs

6. A/D Converter Characteristics at Ta = –30°C to +70°C, V$_{SS}$ = 0 V

Parameter	Symbol	Pins	Conditions		Ratings			Unit
				V$_{DD}$ [V]	min	typ	max	
Resolution	N					8		bit
Absolute precision (Note 2)	ET			4.5 to 6.0			±1/5	LSB
Conversion time	tCAD		A/D conversion time = 16 × tCYC (ADCR2 = 0) (Note 3)	4.5 to 6.0	15.68 (tCYC = 0.98 μs)		65.28 (tCYC = 4.08 μs)	μs
			A/D conversion time = 32 × tCYC (ADCR2 = 1) (Note 3)		31.36 (tCYC = 0.98 μs)		130.56 (tCYC = 4.08 μs)	
Analog input voltage range	V$_{AIN}$	AN0 to AN7		4.5 to 5.5	V$_{SS}$		V$_{DD}$	V
Analog port input current	I$_{AINH}$		V$_{AIN}$ = V$_{DD}$	4.5 to 5.5			+1	μA
	I$_{AINL}$		V$_{AIN}$ = V$_{SS}$	4.5 to 5.5	–1			

(Note 2) Quantizing error (±1/2 LSB) is ignored.
(Note 3) The conversion time is the period from execution of the instruction to start conversion to the completion of shifting the A/D converted value to the register.

7. Current Drain Characteristics at Ta = –30°C to +70°C , V$_{SS}$ = 0 V

Parameter	Symbol	Pins	Conditions		Ratings			Unit
				V$_{DD}$ [V]	min	typ	max	
Current drain during basic operation (Note 4)	I$_{DDOP}$(1)	V$_{DD}$	• FmCF = 12 MHz for ceramic resonator oscillation. • FsXtal = 32.768 kHz for crystal oscillator. • System clock : CF oscillator. • Internal RC oscillator stopped.	4.5 to 6.0		13	26	mA
	I$_{DDOP}$(2)		• FmCF = 3 MHz for ceramic resonator oscillation. • FsXtal = 32.768 kHz for crystal oscillator. • System clock : CF oscillator. • Internal RC oscillator stopped.	4.5 to 6.0		7	14	
	I$_{DDOP}$(3)		• FmCF = 0 Hz (when oscillator stops). • FsXtal = 32.768 kHz for crystal oscillator. • System clock : RC oscillator.	4.5 to 6.0		4	10	
	I$_{DDOP}$(4)		• FmCF = 0 Hz (when oscillator stops). • FsXtal = 32.768 kHz for crystal oscillator. • System clock : crystal oscillator. • Internal RC oscillator stopped.	4.5 to 6.0		4	8	

Parameter	Symbol	Pins	Conditions		Ratings			Unit
				V$_{DD}$ [V]	min	typ	max	
Current drain at HALT mode (Note 4)	I$_{DDHALT}$(1)	V$_{DD}$	• HALT mode • FmCF = 12 MHz for ceramic resonator oscillation. • FsXtal = 32.768 kHz for crystal oscillator. • System clock : CF oscillator. • Internal RC oscillator stopped.	4.5 to 6.0		5	10	mA
	I$_{DDHALT}$(2)		• HALT mode • FmCF = 3 MHz for ceramic resonator oscillation. • FsXtal = 32.768 kHz for crystal oscillator. • System clock : CF oscillator. • Internal RC oscillator stopped.	4.5 to 6.0		2.2	4.6	
	I$_{DDHALT}$(3)		• HALT mode • FmCF = 0 Hz (when oscillator stops). • FsXtal = 32.768 kHz for crystal oscillator. • System clock : RC oscillator	4.5 to 6.0		550	1100	µA
	I$_{DDHALT}$(4)		• HALT mode • FmCF = 0 Hz (when oscillator stops). • FsXtal = 32.768 kHz for crystal oscillator. • System clock : crystal oscillator. • Internal RC oscillator stopped.	4.5 to 6.0		25	100	
Current drain at HOLD mode (Note 4)	I$_{DDHOLD}$(1)	V$_{DD}$	HOLD mode	4.5 to 6.0		0.05	30	
	I$_{DDHOLD}$(2)			2.5 to 4.5		0.02	20	

(Note 4) The currents of output transistors and pull-up transistors are ignored.

Table 1. Ceramic Resonator Oscillation Guaranteed Constants (Main clock)

Oscillation type	Supplier	Oscillator	C1	C2
12 MHz ceramic resonator oscillation	Murata	CSA12.0MTZ	33 pF	33 pF
		CST12.0MTW	on chip	
	Kyocera	KBR-12.0M	33 pF	33 pF
3 MHz ceramic resonator oscillation	Murata	CSA3.00MG040	100 pF	100 pF
		CST3.00MGW040	on chip	
	Kyocera	KBR-3.0MS	47 pF	47 pF

• For both C1 and C2, the K rank (±10%) and SL characteristics must be used.

Table 2. Crystal Oscillaion Guaranteed Constants (Sub-clock)

Oscillation type	Supplier	Oscillator	C3	C4
32.768 kHz crystal oscillation	Kyocera	KF-38G-13P0200	18 pF	18 pF

• For both C3 and C4, the J rank (±5%) and CH characteristics must be used.
  (If high precision is not necessary, use K rank (±10%) and SL characteristics.)

Notes • Since the circuit pattern affects the oscillation frequency, place the oscillation-related parts as close to the oscillation pins as possible with the shortest possible pattern length.
• If you use other oscillators herein, we provide no guarantee for the characteristics.
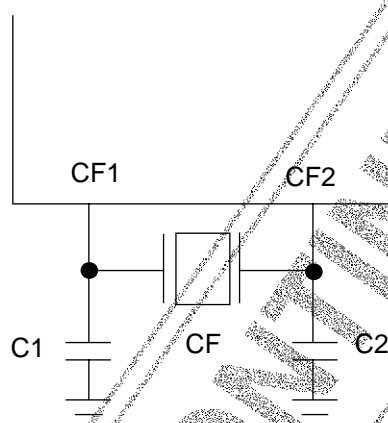
Main-clock circuit
Figure 1 Ceramic Resonator Oscillation
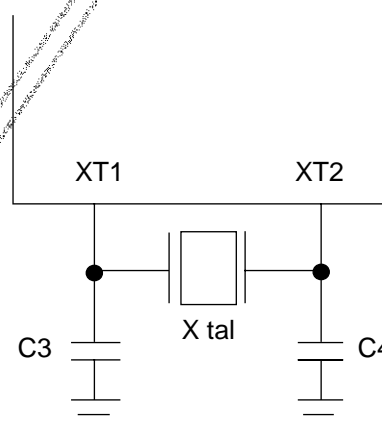
Sub-clock circuit
Figure 2 Crystal Oscillation
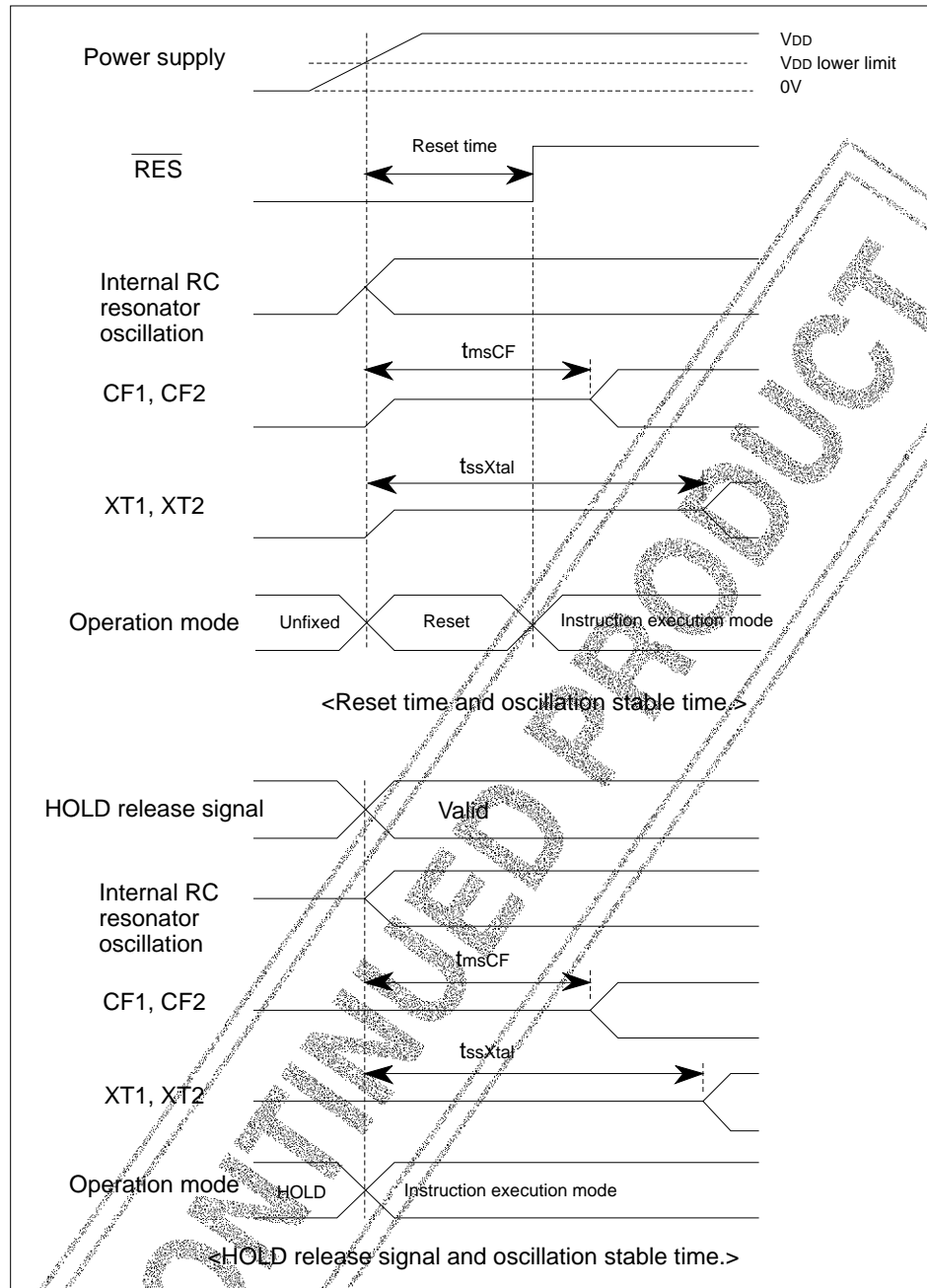
Figure 3　Oscillation Stable Time
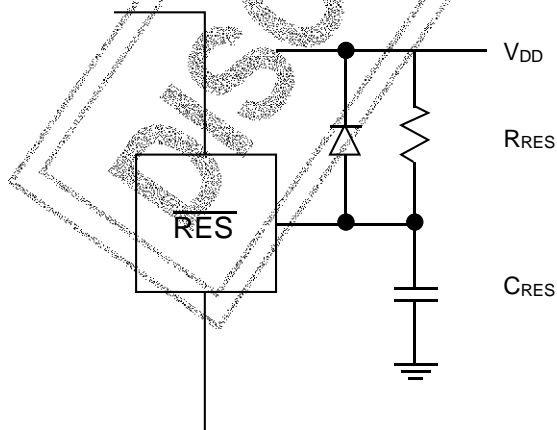
The values of C_{RES} and R_{RES} should be determined such that reset time is at least 200 μs, measured from the moment the power exceeds the V_{DD} lower limit.

Figure 4　Reset Circuit

< AC timing point >

Figure 5   Serial Input/Output Test Conditions

Figure 6   Pulse Input Timing Conditions

Usage Notes

- The construction of the one-time programmable microcontroller with a blank built-in PROM makes it impossible for Sanyo to completely factory-test it before shipping. To prove reliability of the programmed devices, the screening procedure shown in the following figure should always be followed.

- It is not possible to perform a writing test on the blank PROM. 100% yield, therefore, cannot be guaranteed.

- Ensure dry packaging
  The environment must be held at a temparature of 30°C or less and a humidity level of 70% or less.

- After opening the packing
  The preparation procedures shown in the following figure should always be followed prior to mounting the packages on the substrate. After opening the packing, a controlled environment must be maintained until soldering.
  The environment must be held at a temperature of 30°C or less and a humidity level of 70% or less. Please solder within 96 hours.

a. Shipping with a blank PROM (Data to be programmed by customer)

DIP	QFP
Programming and verifying	Programming and verifying

Recommended process of screening

Heat-soak
150 ± 5°C, 24 $^{+1}_{-0}$ Hr

Program reading test

Mounting
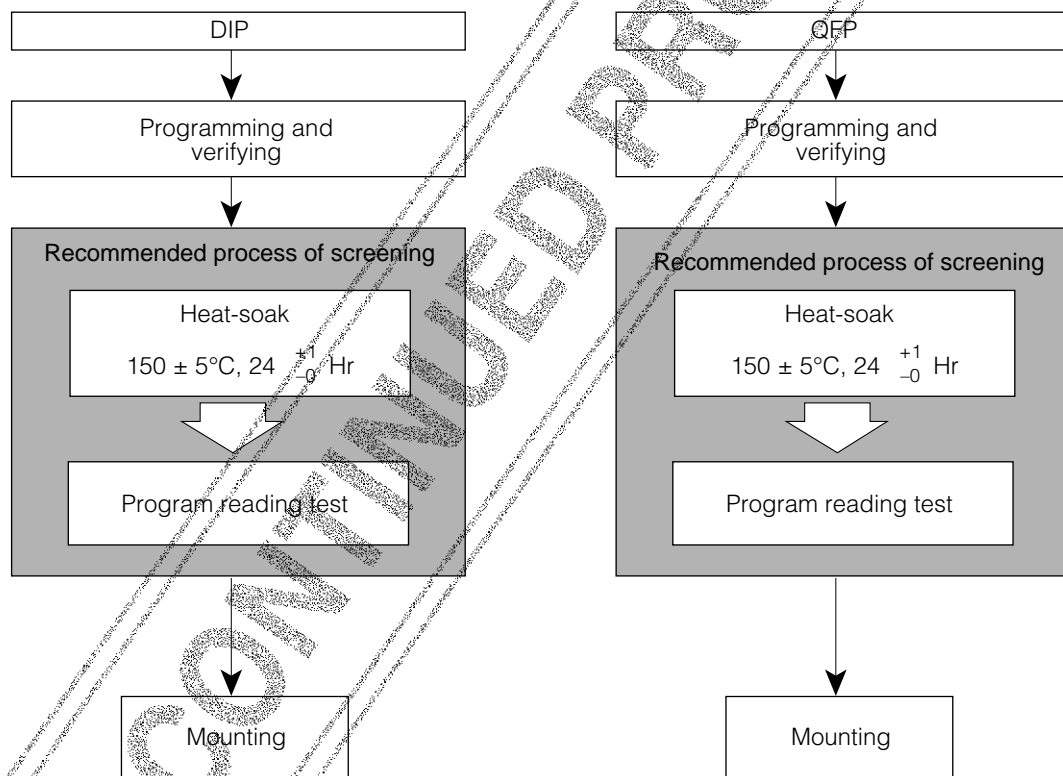
b. Shipping with programmed PROM (Data programmed by Sanyo)

DIP	QFP
Mounting	Mounting

This catalog provides information as of October, 1997. Specifications and information herein are subject to change without notice.